

BID CORRIGENDUM

Tender No : SAC/DPUR/SA202300214801

Tender for: Rate contract of PCB Wiring, Assembly and Testing of QM/FM Payload Electronics card and packages.

Tender Publish Date : 21.03.2024

Bid Due Date:27.05.2024

Based on the pre bid meeting held on 09/04/2024 at SAC related to RFP, Corrigendum issued stating following points.

- Indicative list of ISRO qualified facilities for environmental testing is as below

For Vibration and thermovac – Centum, AMPL, Ananth technologies, Azista etc.
For EMI/EMC – AMPL, Tata Power, SAMIR etc.
- Using SAC facility for CCGA/BGA soldering will be chargeable.
- Following are the details of maximum number of cards / packages in single work order:
TP3 – 5 packages with each package having 6 cards.
Total bank guarantee requirement would be around 30 Cr.
The Bank Guarantee for one supply order may be carry forwarded to next supply order.
- Order will be given to only one vendor and will not split across multiple vendors.
- If the value of FIM is very high compared to the value addition and as such it is essential that the FIM be secured through Bank Guarantee, which shall be valid until supply and acceptance of the final product. However, Bank Guarantee may be waived in the following cases:
 - (a) If a request for waiver of Bank Guarantee towards security of FIM is received from the vendor, the Bank Guarantee may be waived taking into account the track record of the vendor, subject to the conditions that the vendor at his cost, secures the FIM through an all risk insurance cover with the purchaser as the beneficiary.
 - (b) Indemnity Bond may be accepted instead of Bank Guarantee from Central Government Organisations/PSUs/Autonomous Bodies.

In cases where the fabricated product is rejected due to the fault of the fabricator (like not meeting the ordered specifications etc.), fresh raw material/semi-finished product shall not be issued to the vendor free of cost.